

LM1875 20W Audio Power Amplifier

Check for Samples: [LM1875](#)

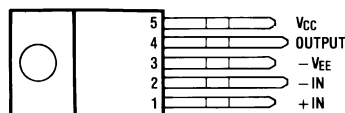
FEATURES

- Up to 30 Watts Output Power
- A_{VO} Typically 90 dB
- Low Distortion: 0.015%, 1 kHz, 20 W
- Wide Power Bandwidth: 70 kHz
- Protection for AC and DC Short Circuits to Ground
- Thermal Protection with Parole Circuit
- High Current Capability: 4A
- Wide Supply Range 16V-60V
- Internal Output Protection Diodes
- 94 dB Ripple Rejection
- Plastic Power Package TO-220

APPLICATIONS

- High Performance Audio Systems
- Bridge Amplifiers
- Stereo Phonographs
- Servo Amplifiers
- Instrument Systems

Connection Diagram



**Figure 1. NDH0005D, KC0005A,
NEB0005E, NEB0005B,
Front View**

DESCRIPTION

The LM1875 is a monolithic power amplifier offering very low distortion and high quality performance for consumer audio applications.

The LM1875 delivers 20 watts into a 4Ω or 8Ω load on ±25V supplies. Using an 8Ω load and ±30V supplies, over 30 watts of power may be delivered. The amplifier is designed to operate with a minimum of external components. Device overload protection consists of both internal current limit and thermal shutdown.

The LM1875 design takes advantage of advanced circuit techniques and processing to achieve extremely low distortion levels even at high output power levels. Other outstanding features include high gain, fast slew rate and a wide power bandwidth, large output voltage swing, high current capability, and a very wide supply range. The amplifier is internally compensated and stable for gains of 10 or greater.



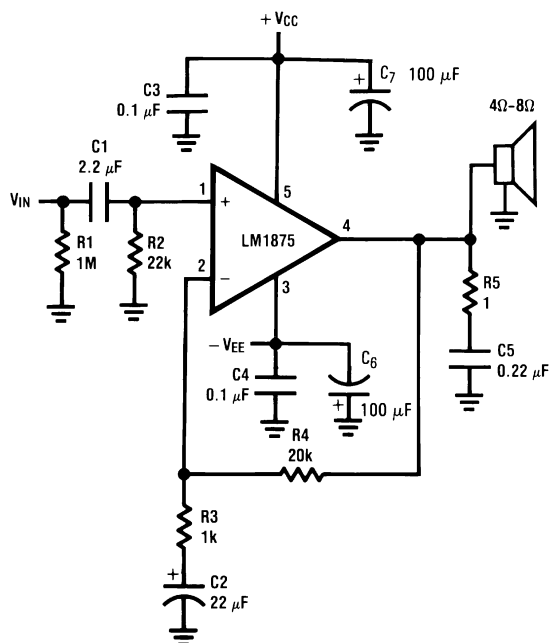
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 2004, Texas Instruments Incorporated

Typical Applications



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage		60V
Input Voltage		$-V_{EE}$ to V_{CC}
Storage Temperature		-65°C to $+150^{\circ}\text{C}$
Junction Temperature		150°C
Lead Temperature	(Soldering, 10 seconds)	260°C
	θ_{JC}	3°C
	θ_{JA}	73°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.

Electrical Characteristics

$V_{CC}=+25V$, $-V_{EE}=-25V$, $T_{AMBIENT}=25^{\circ}C$, $R_L=8\Omega$, $A_V=20$ (26 dB), $f_o=1$ kHz, unless otherwise specified.

Parameter	Conditions	Typical	Tested Limits	Units
Supply Current	$P_{OUT}=0W$	70	100	mA
Output Power ⁽¹⁾	THD=1%	25		W
THD ⁽¹⁾	$P_{OUT}=20W$, $f_o=1$ kHz	0.015		%
	$P_{OUT}=20W$, $f_o=20$ kHz	0.05	0.4	%
	$P_{OUT}=20W$, $R_L=4\Omega$, $f_o=1$ kHz	0.022		%
	$P_{OUT}=20W$, $R_L=4\Omega$, $f_o=20$ kHz	0.07	0.6	%
Offset Voltage		± 1	± 15	mV
Input Bias Current		± 0.2	± 2	μA
Input Offset Current		0	± 0.5	μA
Gain-Bandwidth Product	$f_o=20$ kHz	5.5		MHz
Open Loop Gain	DC	90		dB
PSRR	V_{CC} , 1 kHz, 1 Vrms	95	52	dB
	V_{EE} , 1 kHz, 1 Vrms	83	52	dB
Max Slew Rate	20W, 8 Ω , 70 kHz BW	8		V/ μs
Current Limit	$V_{OUT} = V_{SUPPLY} - 10V$	4	3	A
Equivalent Input Noise Voltage	$R_S=600\Omega$, CCIR	3		$\mu Vrms$

- (1) Assumes the use of a heat sink having a thermal resistance of $1^{\circ}C/W$ and no insulator with an ambient temperature of $25^{\circ}C$. Because the output limiting circuitry has a negative temperature coefficient, the maximum output power delivered to a 4 Ω load may be slightly reduced when the tab temperature exceeds $55^{\circ}C$.

Typical Applications For Single Supply Operation

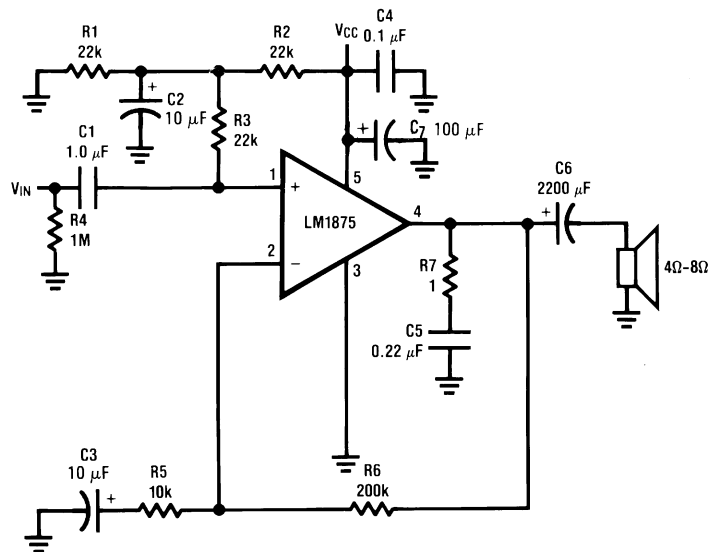


Figure 2.

Typical Performance Characteristics

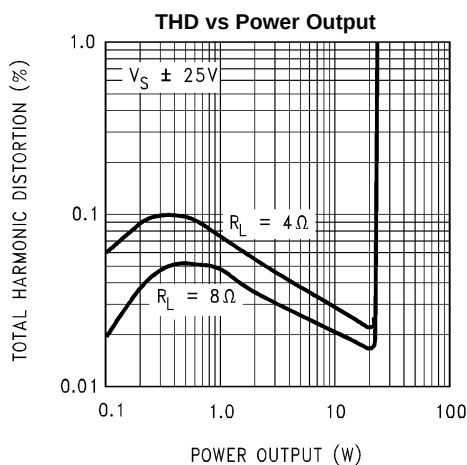


Figure 3.

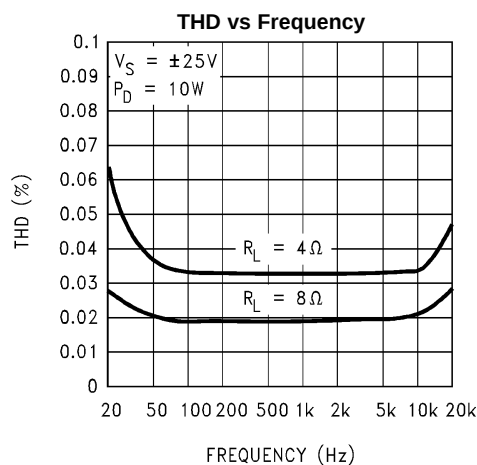


Figure 4.

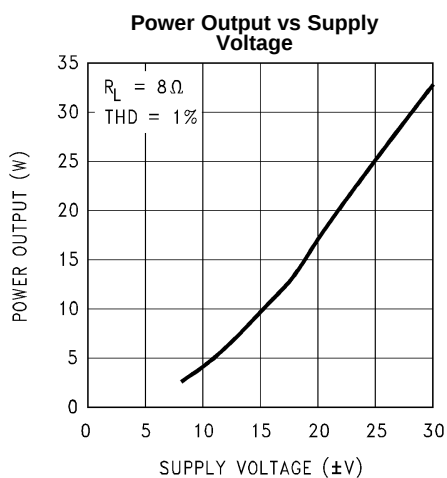


Figure 5.

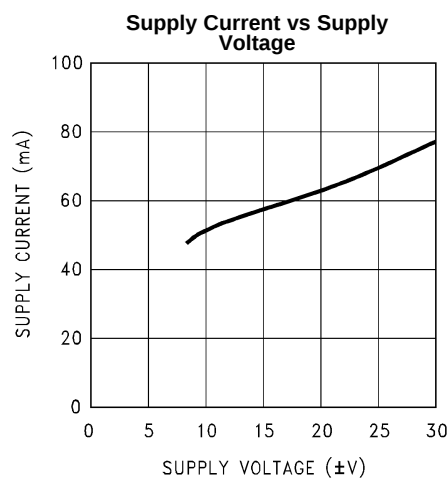


Figure 6.

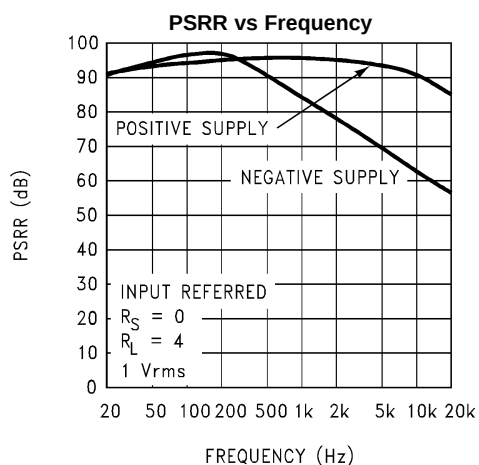


Figure 7.

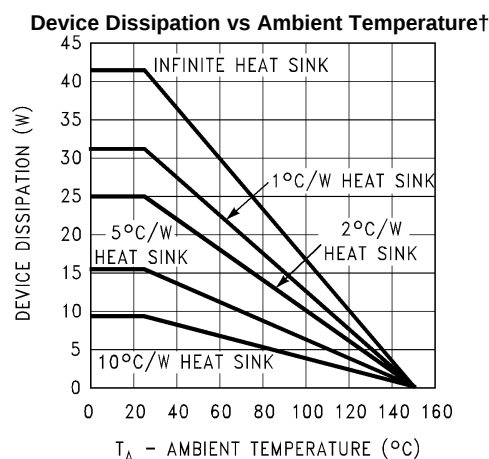


Figure 8.

† ϕ INTERFACE = 1°C/W.
See [Application Hints](#).

Typical Performance Characteristics (continued)

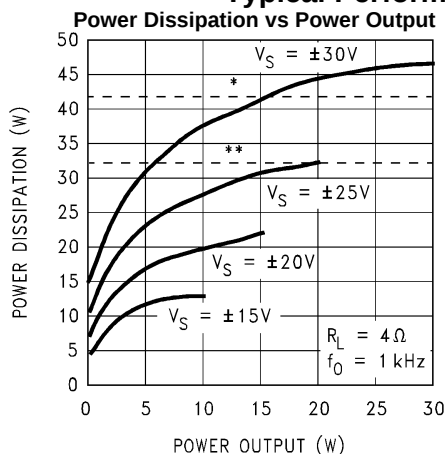


Figure 9.

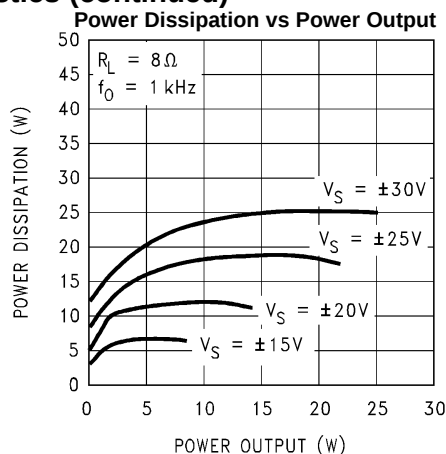


Figure 10.

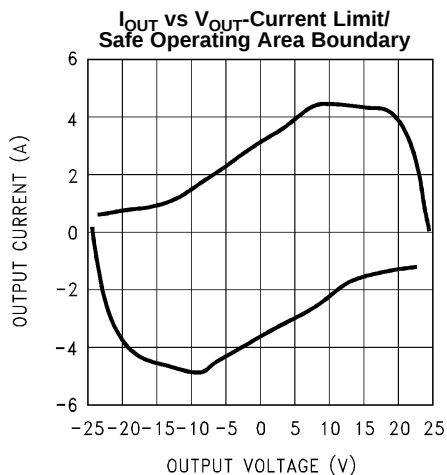
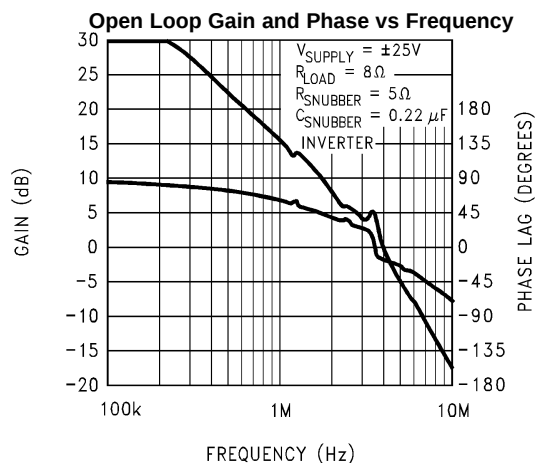


Figure 11.



Thermal shutdown with infinite heat sink

Thermal shutdown with 1°C/W heat sink

Figure 12.

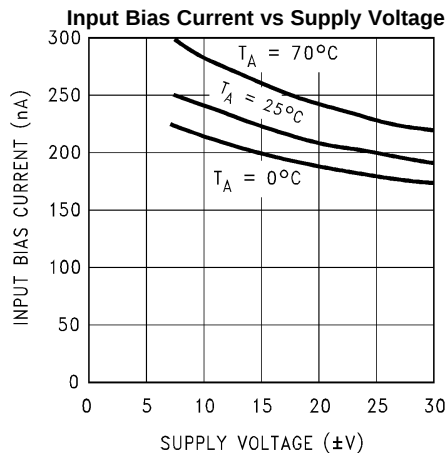


Figure 13.

APPLICATION HINTS

STABILITY

The LM1875 is designed to be stable when operated at a closed-loop gain of 10 or greater, but, as with any other high-current amplifier, the LM1875 can be made to oscillate under certain conditions. These usually involve printed circuit board layout or output/input coupling.

Proper layout of the printed circuit board is very important. While the LM1875 will be stable when installed in a board similar to the ones shown in this data sheet, it is sometimes necessary to modify the layout somewhat to suit the physical requirements of a particular application. When designing a different layout, it is important to return the load ground, the output compensation ground, and the low level (feedback and input) grounds to the circuit board ground point through separate paths. Otherwise, large currents flowing along a ground conductor will generate voltages on the conductor which can effectively act as signals at the input, resulting in high frequency oscillation or excessive distortion. It is advisable to keep the output compensation components and the 0.1 μF supply decoupling capacitors as close as possible to the LM1875 to reduce the effects of PCB trace resistance and inductance. For the same reason, the ground return paths for these components should be as short as possible.

Occasionally, current in the output leads (which function as antennas) can be coupled through the air to the amplifier input, resulting in high-frequency oscillation. This normally happens when the source impedance is high or the input leads are long. The problem can be eliminated by placing a small capacitor (on the order of 50 pF to 500 pF) across the circuit input.

Most power amplifiers do not drive highly capacitive loads well, and the LM1875 is no exception. If the output of the LM1875 is connected directly to a capacitor with no series resistance, the square wave response will exhibit ringing if the capacitance is greater than about 0.1 μF . The amplifier can typically drive load capacitances up to 2 μF or so without oscillating, but this is not recommended. If highly capacitive loads are expected, a resistor (at least 1 Ω) should be placed in series with the output of the LM1875. A method commonly employed to protect amplifiers from low impedances at high frequencies is to couple to the load through a 10 Ω resistor in parallel with a 5 μH inductor.

DISTORTION

The preceding suggestions regarding circuit board grounding techniques will also help to prevent excessive distortion levels in audio applications. For low THD, it is also necessary to keep the power supply traces and wires separated from the traces and wires connected to the inputs of the LM1875. This prevents the power supply currents, which are large and nonlinear, from inductively coupling to the LM1875 inputs. Power supply wires should be twisted together and separated from the circuit board. Where these wires are soldered to the board, they should be perpendicular to the plane of the board at least to a distance of a couple of inches. With a proper physical layout, THD levels at 20 kHz with 10W output to an 8 Ω load should be less than 0.05%, and less than 0.02% at 1 kHz.

CURRENT LIMIT AND SAFE OPERATING AREA (SOA) PROTECTION

A power amplifier's output transistors can be damaged by excessive applied voltage, current flow, or power dissipation. The voltage applied to the amplifier is limited by the design of the external power supply, while the maximum current passed by the output devices is usually limited by internal circuitry to some fixed value. Short-term power dissipation is usually not limited in monolithic audio power amplifiers, and this can be a problem when driving reactive loads, which may draw large currents while high voltages appear on the output transistors. The LM1875 not only limits current to around 4A, but also reduces the value of the limit current when an output transistor has a high voltage across it.

When driving nonlinear reactive loads such as motors or loudspeakers with built-in protection relays, there is a possibility that an amplifier output will be connected to a load whose terminal voltage may attempt to swing beyond the power supply voltages applied to the amplifier. This can cause degradation of the output transistors or catastrophic failure of the whole circuit. The standard protection for this type of failure mechanism is a pair of diodes connected between the output of the amplifier and the supply rails. These are part of the internal circuitry of the LM1875, and needn't be added externally when standard reactive loads are driven.

THERMAL PROTECTION

The LM1875 has a sophisticated thermal protection scheme to prevent long-term thermal stress to the device. When the temperature on the die reaches 170°C, the LM1875 shuts down. It starts operating again when the die temperature drops to about 145°C, but if the temperature again begins to rise, shutdown will occur at only 150°C. Therefore, the device is allowed to heat up to a relatively high temperature if the fault condition is temporary, but a sustained fault will limit the maximum die temperature to a lower value. This greatly reduces the stresses imposed on the IC by thermal cycling, which in turn improves its reliability under sustained fault conditions.

Since the die temperature is directly dependent upon the heat sink, the heat sink should be chosen for thermal resistance low enough that thermal shutdown will not be reached during normal operation. Using the best heat sink possible within the cost and space constraints of the system will improve the long-term reliability of any power semiconductor device.

POWER DISSIPATION AND HEAT SINKING

The LM1875 must always be operated with a heat sink, even when it is not required to drive a load. The maximum idling current of the device is 100 mA, so that on a 60V power supply an unloaded LM1875 must dissipate 6W of power. The 54°C/W junction-to-ambient thermal resistance of a TO-220 package would cause the die temperature to rise 324°C above ambient, so the thermal protection circuitry will shut the amplifier down if operation without a heat sink is attempted.

In order to determine the appropriate heat sink for a given application, the power dissipation of the LM1875 in that application must be known. When the load is resistive, the maximum average power that the IC will be required to dissipate is approximately:

$$P_{D(MAX)} \approx \frac{V_S^2}{2\pi^2 R_L} + P_Q$$

where

- V_S is the total power supply voltage across the LM1875
- R_L is the load resistance
- P_Q is the quiescent power dissipation of the amplifier

The above equation is only an approximation which assumes an “ideal” class B output stage and constant power dissipation in all other parts of the circuit. The curves of “Power Dissipation vs Power Output” give a better representation of the behavior of the LM1875 with various power supply voltages and resistive loads. As an example, if the LM1875 is operated on a 50V power supply with a resistive load of 8Ω, it can develop up to 19W of internal power dissipation. If the die temperature is to remain below 150°C for ambient temperatures up to 70°C, the total junction-to-ambient thermal resistance must be less than

$$\frac{150^\circ\text{C} - 70^\circ\text{C}}{19\text{W}} = 4.2^\circ\text{C/W}.$$

Using $\theta_{JC} = 2^\circ\text{C/W}$, the sum of the case-to-heat-sink interface thermal resistance and the heat-sink-to-ambient thermal resistance must be less than 2.2°C/W. The case-to-heat-sink thermal resistance of the TO-220 package varies with the mounting method used. A metal-to-metal interface will be about 1°C/W if lubricated, and about 1.2°C/W if dry.

If a mica insulator is used, the thermal resistance will be about 1.6°C/W lubricated and 3.4°C/W dry. For this example, we assume a lubricated mica insulator between the LM1875 and the heat sink. The heat sink thermal resistance must then be less than

$$4.2^\circ\text{C/W} - 2^\circ\text{C/W} - 1.6^\circ\text{C/W} = 0.6^\circ\text{C/W}.$$

This is a rather large heat sink and may not be practical in some applications. If a smaller heat sink is required for reasons of size or cost, there are two alternatives. [EM00001]The maximum ambient operating temperature can be reduced to 50°C (122°F), resulting in a 1.6°C/W heat sink, or the heat sink can be isolated from the chassis so the mica washer is not needed. This will change the required heat sink to a 1.2°C/W unit if the case-to-heat-sink interface is lubricated.

When using a single supply, maximum transfer of heat away from the LM1875 can be achieved by mounting the device directly to the heat sink (tab is at ground potential); this avoids the use of a mica or other type insulator.

The thermal requirements can become more difficult when an amplifier is driving a reactive load. For a given magnitude of load impedance, a higher degree of reactance will cause a higher level of power dissipation within the amplifier. As a general rule, the power dissipation of an amplifier driving a 60° reactive load (usually considered to be a worst-case loudspeaker load) will be roughly that of the same amplifier driving the resistive part of that load. For example, a loudspeaker may at some frequency have an impedance with a magnitude of 8Ω and a phase angle of 60°. The real part of this load will then be 4Ω, and the amplifier power dissipation will roughly follow the curve of power dissipation with a 4Ω load.

Component Layouts

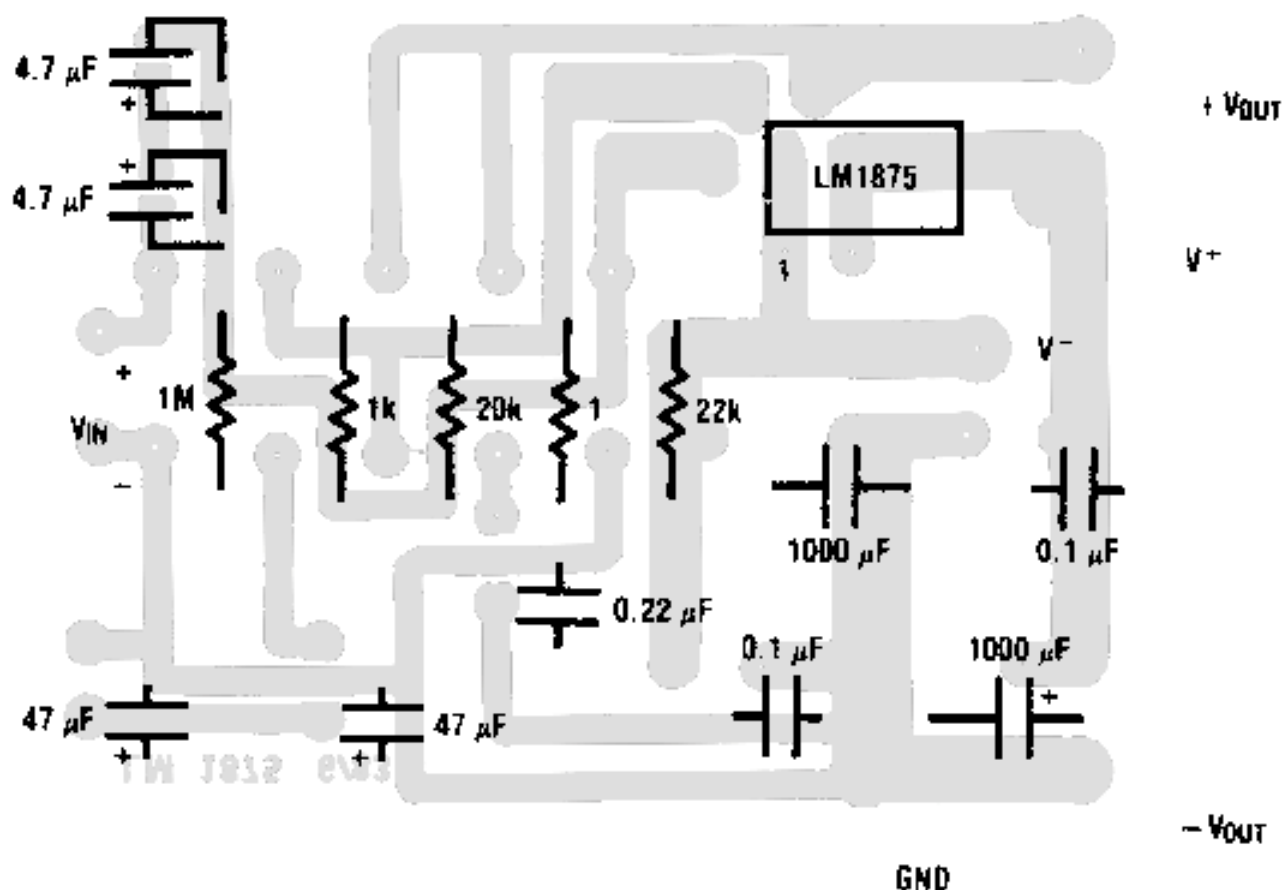


Figure 14. Split Supply

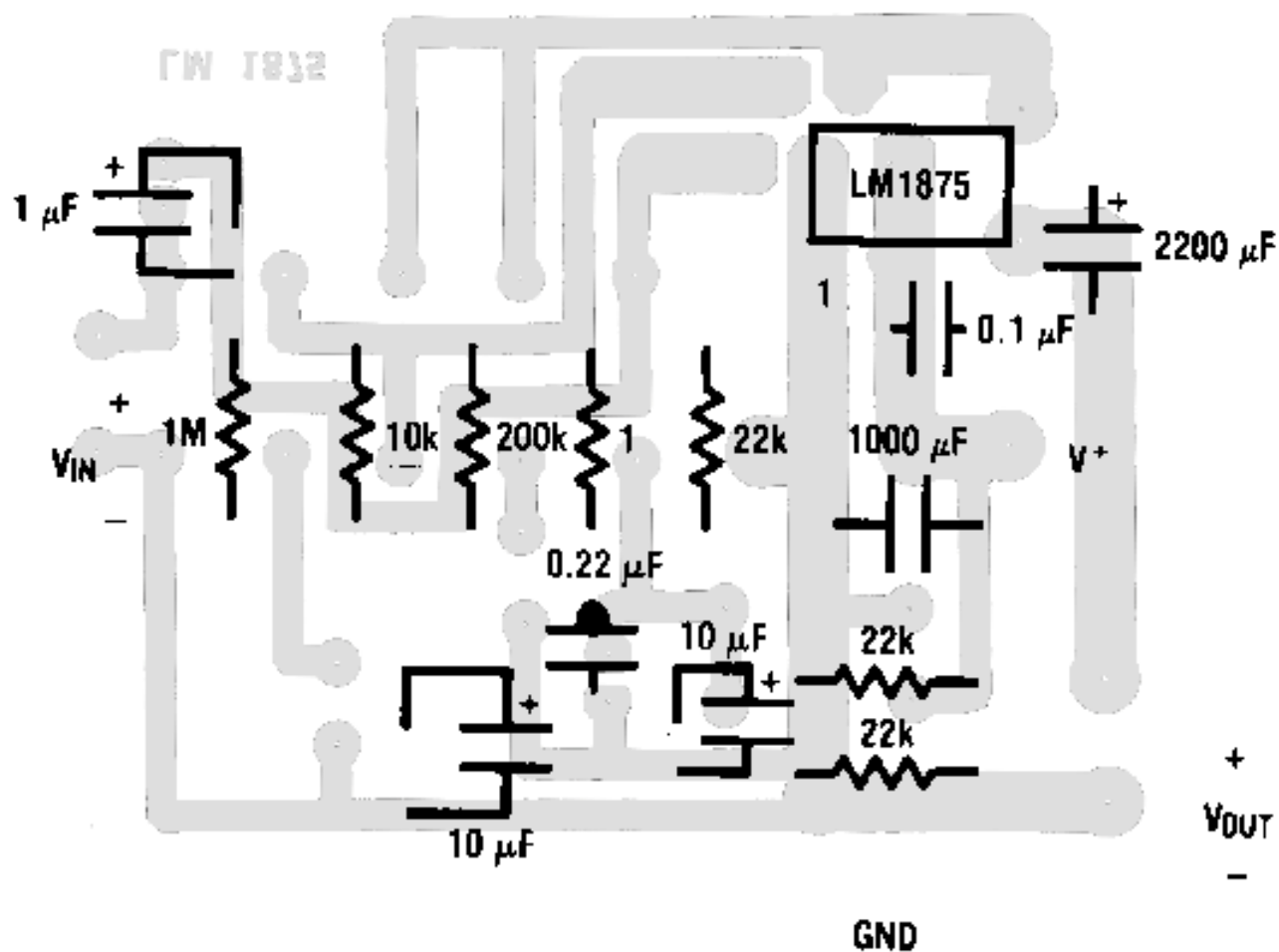


Figure 15. Single Supply

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM1875T	ACTIVE	TO-220	NDH	5	45	TBD	Call TI	Call TI	0 to 70	LM1875T	Samples
LM1875T/LB02	ACTIVE	TO-220	NEB	5	45	TBD	Call TI	Call TI		LM1875T	Samples
LM1875T/LB03	ACTIVE	TO-220	NDH	5	45	TBD	Call TI	Call TI		LM1875T	Samples
LM1875T/LB05	ACTIVE	TO-220	NEB	5	45	TBD	Call TI	Call TI		LM1875T	Samples
LM1875T/LF02	ACTIVE	TO-220	NEB	5	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM		LM1875T	Samples
LM1875T/LF03	ACTIVE	TO-220	NDH	5	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM		LM1875T	Samples
LM1875T/LF05	ACTIVE	TO-220	NEB	5	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM		LM1875T	Samples
LM1875T/NOPB	ACTIVE	TO-220	NDH	5	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM1875T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

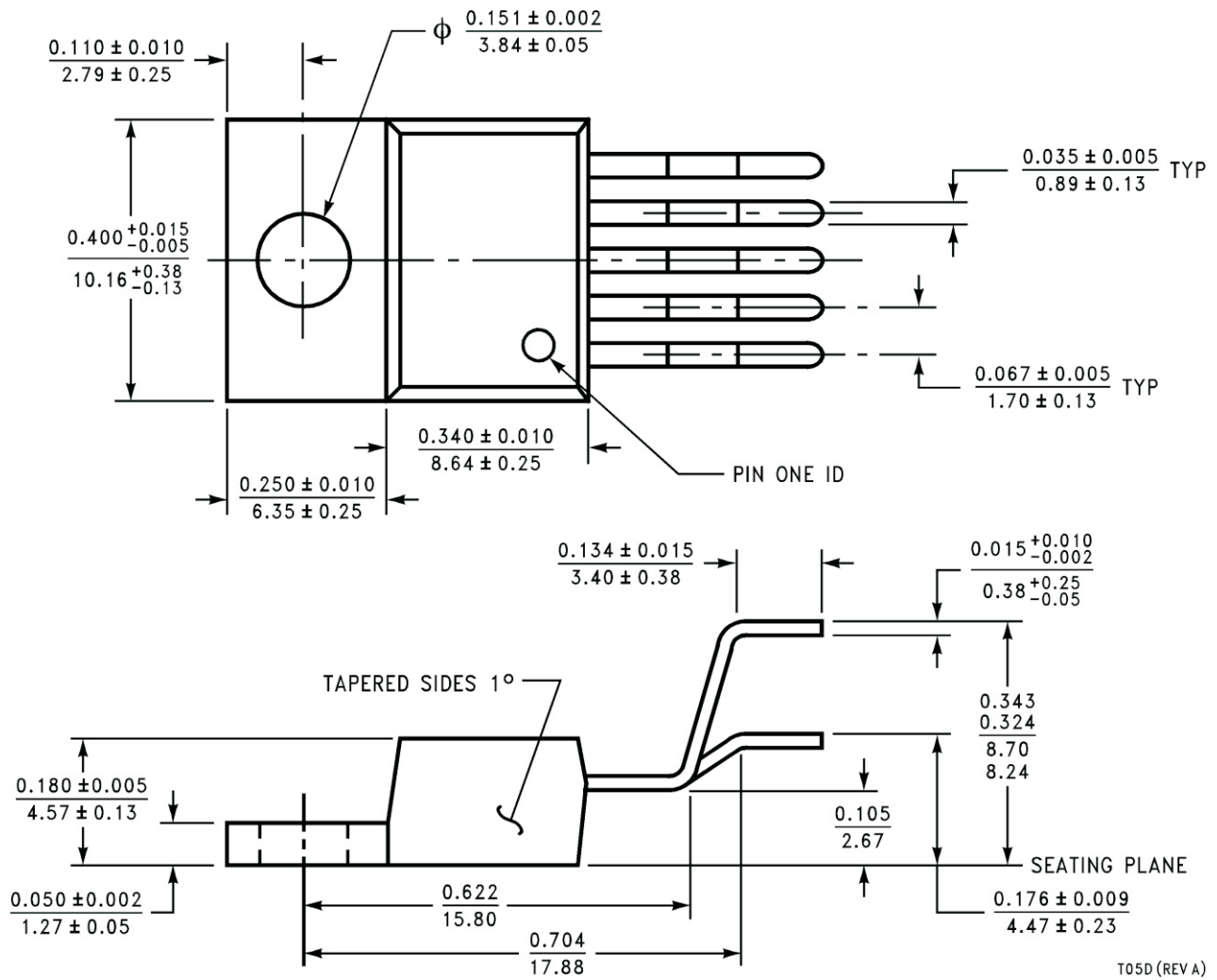
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

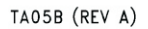
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

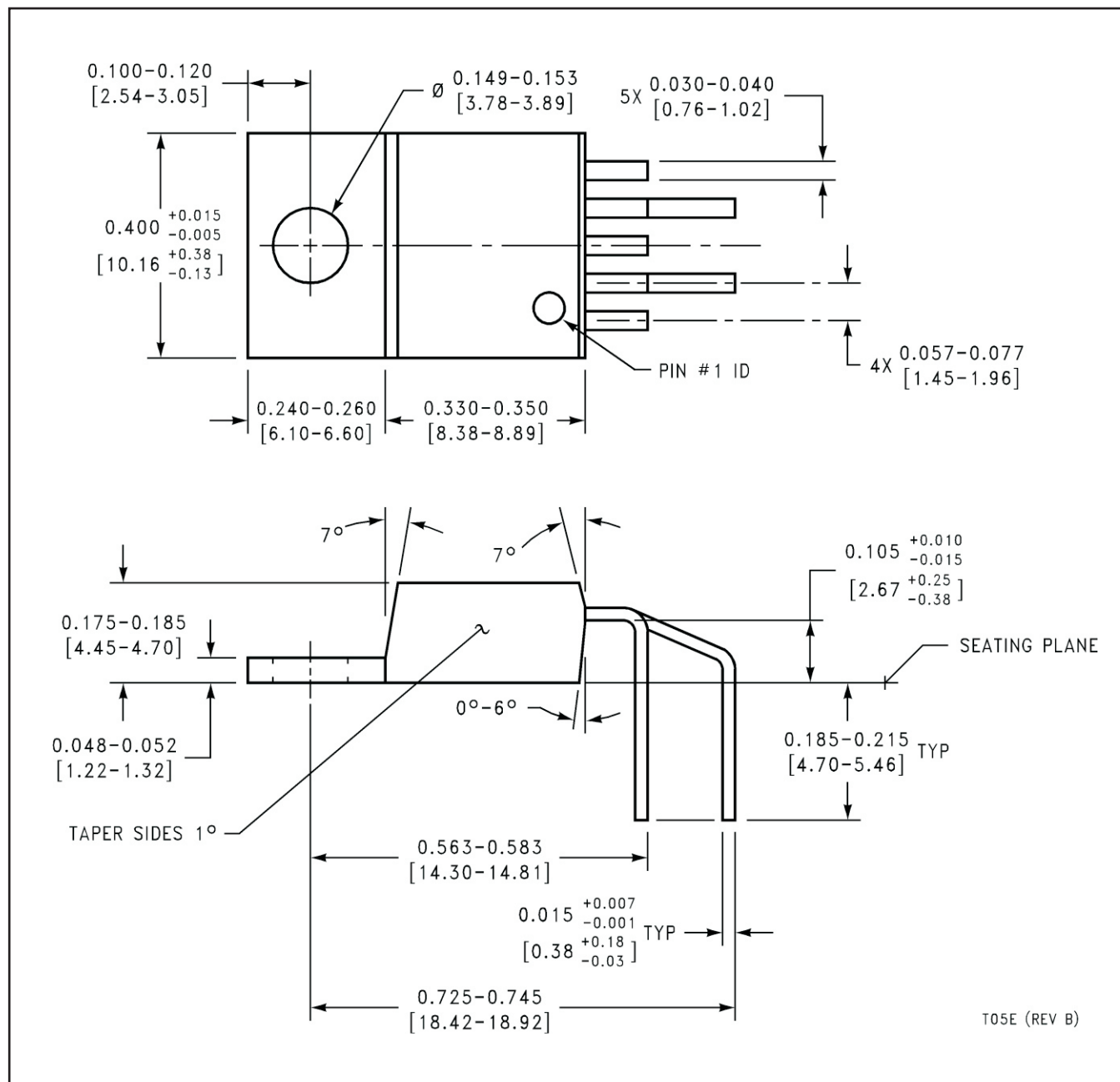
NDH0005D



NEB0005B



NEB0005E



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com